NEC

NEC Electronics Inc.

μPD4168
8,192 x 8-BIT NMOS XRAM

Revision 1

Description

The NEC μPD4168 is an 8,192 word by 8-bit NMOS XRAM designed to operate from a single +5 V power supply. The NEC μPD4168 is termed an XRAM because it incorporates some of the best features of both SRAMs (Non-multiplexed addresses, simple interface requirements) and DRAMs (the one-transistor core cell provides high density at low cost). The negative voltage substrate bias is internally generated and provides automatic and transparent operation.

The incorporation of an internal refresh address counter and refresh multiplexer allows the user to select one of three refresh modes. The self-refresh mode provides transparent refresh without system overhead. Internal latches for address, data, and chip select allow for use in systems incorporating multiplexed address/data buses.

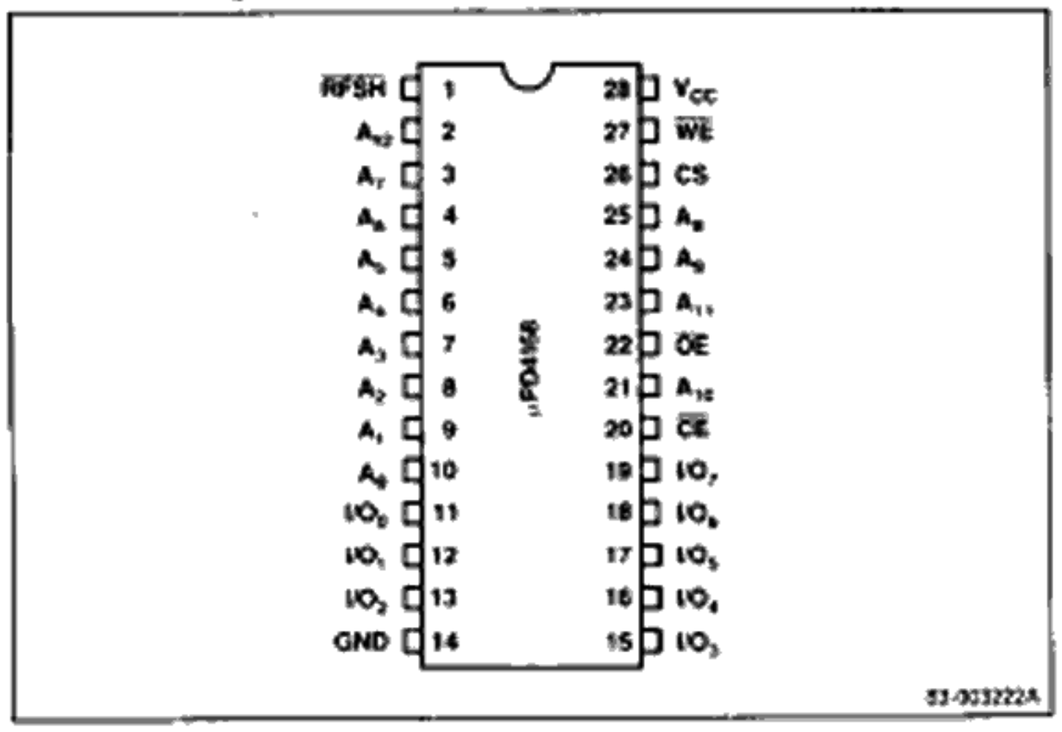
Features

- ☐ 8,192 words by 8-bit organization
- ☐ Single +5 V ± 10% power supply
- ☐ On-chip substrate bias generator
- ☐ Fast access times
- ☐ Low power dissipation:
  28 mW max–Standby
  19 mW max–Self refresh
- ☐ TTL-compatible
- ☐ 28-pin SRAM/ROM/EPROM compatible package
- ☐ Built-in refresh multiplexer and refresh address counter
- ☐ Power-down self-refresh mode
- ☐ Automatic precharge allows cycle time to be independent of system skews
- ☐ Latched address, CS, and $\overline{OE}$ functions allow use on multiplexed address/data bus
- ☐ Read, early write, late write, external refresh, pulse refresh, and self-refresh cycles

Performance Ranges

Device	t_{CEA}	t_{OEA}	t_C	I_{CC1}
μPD4168C–12	120 ns	45 ns	220 ns	65 mA
μPD4168C–15	150 ns	55 ns	260 ns	60 mA
μPD4168C–20	200 ns	70 ns	330 ns	55 mA

Pin Configuration



Pin Identification

No.	Symbol	Function
1	$\overline{RFSH}$	Internal refresh
2–10, 21, 23–25	A_0–A_{12}	Address inputs
11–13, 15–19	I/O_0–I/O_7	Data in/out
14	GND	Ground
20	$\overline{CE}$	Chip enable
22	$\overline{OE}$	Output enable
26	CS	Chip select
27	$\overline{WE}$	Write enable
28	V_{CC}	+5 V power supply

Pin Functions

$\overline{RFSH}$ (Refresh Input)

A built-in refresh control circuit enables this input. Two refresh modes are available: pulse refresh, using the $\overline{RFSH}$ input as a clock input, and power-down self-refresh, using the $\overline{RFSH}$ input as logic level input. $\overline{RFSH}$ is high (inactive) during normal read and write cycles.

A_0–A_{12} (Address Inputs)

The μPD4168 requires 13 address inputs to select a word of data. Because these address inputs are internally read onto the chip at the falling edge of a $\overline{CE}$ clock pulse, the $\overline{CE}$ clock determines their address setup and hold times. Inputs A_0–A_6 perform external refresh.

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I/O_0–I/O_7 (Data Inputs/Outputs)

Common I/O pins require $\overline{WE}$ and $\overline{OE}$ to control data. The $\overline{CE}$ clock and $\overline{WE}$ determine the data setup and hold times (t_{DSC}, t_{DHC}, t_{DSW}, t_{DHW}) for these pins during a memory write cycle; $\overline{OE}$ determines the access time (t_{OEA}) during a read cycle.

GND (Ground)

All voltages are referenced to GND.

$\overline{CE}$ (Chip Enable)

The chip enable clock initiates read/write cycles and external refresh cycles. It allows addresses, CS, and (during an early write cycle) data inputs to be internally read onto the chip.

$\overline{OE}$ (Output Enable)

$\overline{OE}$ controls the output timing for I/O_0–I/O_7. Access time (t_{CEA}, t_{OEA}) is determined by the $\overline{CE}$ clock or by the $\overline{OE}$ input, according to $\overline{OE}$ input timing.

CS (Chip Select)

When CS is high (active) while the $\overline{CE}$ clock is enabled, the μPD4168 can perform read/write operations. If CS is latched low (inactive) while the $\overline{CE}$ clock is enabled, I/O_0–I/O_7 remain in the high-impedance state, regardless of the status of $\overline{WE}$ and $\overline{OE}$.

$\overline{WE}$ (Write Enable)

$\overline{WE}$ controls read/write operations. $\overline{WE}$ input timing determines whether a write cycle is an early write or a late write.

V_{CC} (Power Supply)

+5 V power supply.

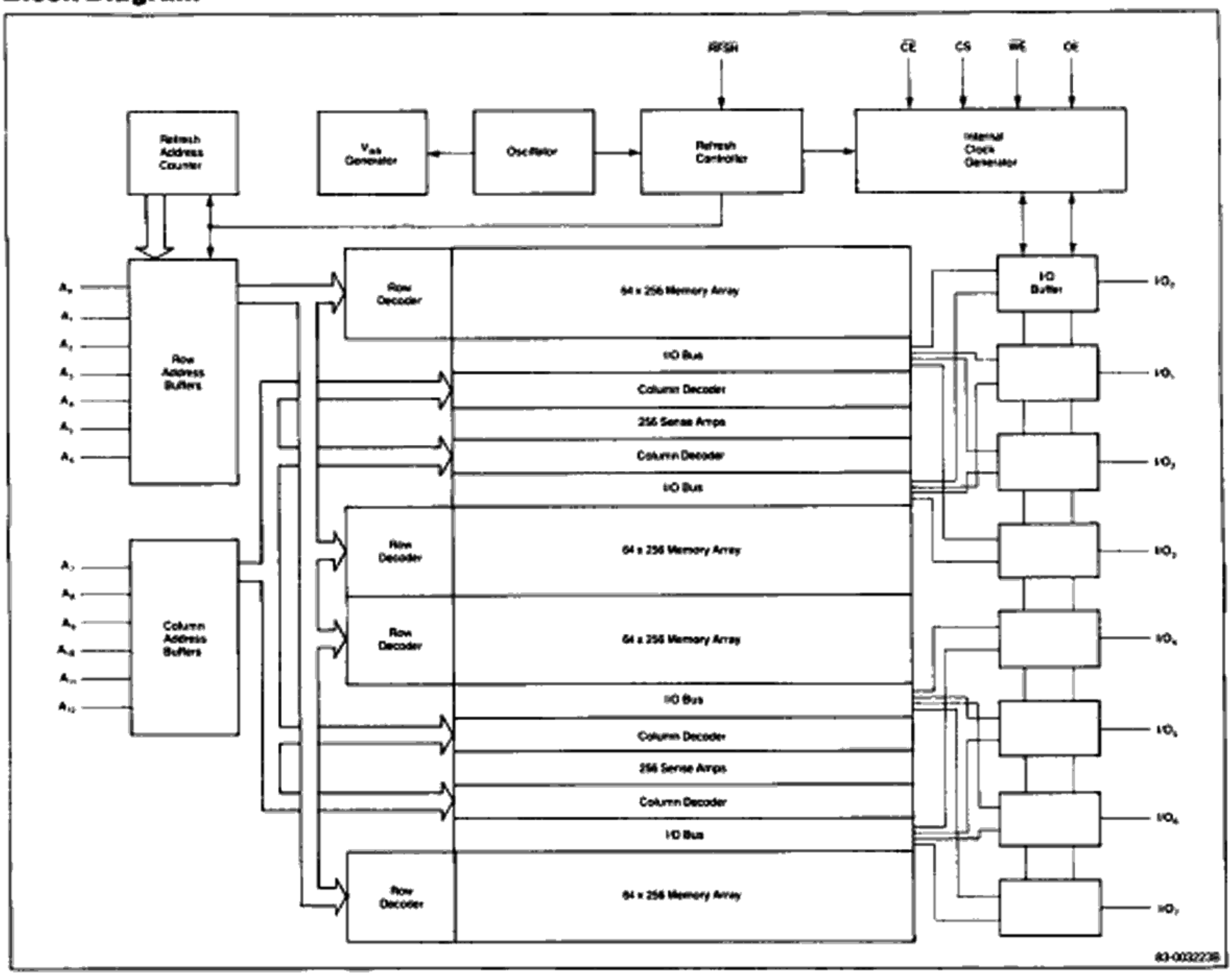
μPD4168 Functional Modes

Mode	$\overline{RFSH}$	$\overline{CE}$	CS	$\overline{WE}$	$\overline{OE}$	I/O	Comments
Read cycle	H	C′	H	H	L	Data out	$\overline{OE}$: low logic level or clock pulse
Early write	H	C′	H	L	H	Data in	
Late Write	H	C′	H	C′	H	Data in	
External refresh	H	C′	H	H	H	High-Z	
	H	C′	L	X	X	High-Z	Standby
Pulse refresh	C′	H	X	X	X	High-Z	
	C′	C′	H	H	H	High-Z	After external refresh cycle
	C′	C′	H	H	L	(Note 1)	After read cycle
	C′	C′	H	L	H	Data in	After early write cycle
	C′	C′	H	C′	H	Data in	After late write cycle
Power down self-refresh	L	H	X	X	X	High-Z	
Standby	H	H	X	X	X	High-Z	

H = V_{IH}, L = V_{IL}, C′ = negative edge of clock pulse, X = V_{IH} or V_{IL}

Note:
(1) Depends on previous cycle

Block Diagram



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Absolute Maximum Ratings

Voltage on any pin relative to GND	−1.0 to +7.0 V
Operating temperature, T_{OPR}	0 to +70°C
Storage temperature, T_{STG}	−55 to +125°C
Short circuit output current, I_{OS}	50 mA
Power dissipation, P_D	1 W

Comment: Exposing the device to stresses above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational sections of the specification. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

$T_A = 0$ to $+70°C$; $V_{CC} = 5V \pm 10\%$

Parameter	Symbol	Limits Min	Typ	Max	Unit	Test Conditions
Supply voltage	V_{CC}	4.5	5.0	5.5	V	Referenced to GND
Input voltage, low	V_{IL}	−1.0		0.8	V	Referenced to GND
Input voltage, high	V_{IH}	2.4		5.5	V	Referenced to GND
Output voltage, low	V_{OL}	0		0.4	V	$I_{OL} = 2$ mA

DC Characteristics (cont)

Parameter	Symbol	Limits Min	Typ	Max	Unit	Test Conditions
Output voltage, high	V_{OH}	2.4		V_{CC}	V	$I_{OH} = -1$ mA
Average V_{CC} supply current, active	I_{CC1}			65	mA	$t_C = 220$ ns
				60	mA	$t_C = 260$ ns
				55	mA	$t_C = 330$ ns
Standby current	I_{CC2}			5	mA	$\overline{CE} \geq V_{IH}$ min, $\overline{RFSH} \geq V_{IH}$ min
Self-refresh average current	I_{CC3}			3.5	mA	$\overline{RFSH} \leq V_{IL}$ max
Input leakage current	$I_{I(L)}$	−10		10	μA	$V_{IN} = 0$ to 5.5 V; others = 0 V
Output leakage current	$I_{O(L)}$	−10		10	μA	$V_{OUT} = 0$ to 5.5 V; D_{OUT} = High-Z

Capacitance

$T_A = 0$ to +70°C, $V_{CC} = 5.0$ V ±10%

Parameter	Symbol	Limits Min	Typ	Max	Unit	Test Conditions
Input capacitance	C_I			10	pF	f = 1 MHz
Data I/O capacitance	$C_{I/O}$			10	pF	f = 1 MHz

AC Characteristics

$T_A = 0$ to +70°C, $V_{CC} = 5$ V ±10%

Parameter	Symbol	Limits μPD4168-12 Min	μPD4168-12 Max	μPD4168-15 Min	μPD4168-15 Max	μPD4168-20 Min	μPD4168-20 Max	Unit	Test Conditions
Average V_{CC} supply current, active	I_{CC1}		65		60		55	mA	$t_C = t_C$ (min)
Read, write, or refresh cycle time	t_C	220		260		330		ns	
Access time from $\overline{CE}$	t_{CEA}		120		150		200	ns	(Note 5)
Data off time from $\overline{CE}$	t_{CEZ}		30		35		45	ns	(Note 6)
Access time from $\overline{OE}$	t_{OEA}		45		55		70	ns	(Note 5)
Data off time from $\overline{OE}$	t_{OEZ}		30		35		45	ns	(Note 6)
$\overline{CE}$ pulse width	t_{CE}	120	10000	150	10000	200	10000	ns	
$\overline{CE}$ precharge time	t_P	90		100		120		ns	
Address setup time to $\overline{CE}$	t_{ASC}	0		0		0		ns	
Address hold time from $\overline{CE}$	t_{AHC}	35		45		55		ns	
CS setup time to $\overline{CE}$	t_{CSC}	0		0		0		ns	
CS hold time from $\overline{CE}$	t_{CHC}	35		45		55		ns	
Data setup time to $\overline{CE}$, early write	t_{DSC}	−10		−10		−10		ns	
Data hold time from $\overline{CE}$, early write	t_{DHC}	90		100		120		ns	
Data setup time to $\overline{WE}$, late write	t_{DSW}	0		0		0		ns	
Data hold time from $\overline{WE}$, late write	t_{DHW}	50		60		70		ns	
$\overline{WE}$ setup time to $\overline{CE}$, early write	t_{WSC}	−30		−30		−30		ns	(Note 7)
$\overline{WE}$ hold time from $\overline{CE}$, early write	t_{WHC}	90		100		125		ns	
$\overline{WE}$ pulse duration	t_{WD}	60		70		90		ns	
$\overline{CE}$ hold time from $\overline{WE}$, late write	t_{CHW}	90		105		135		ns	
$\overline{WE}$ setup time to $\overline{CE}$, read cycle	t_{RCS}	0		0		0		ns	
$\overline{WE}$ hold time from $\overline{CE}$, read cycle	t_{RCH}	0		0		0		ns	
$\overline{CE}$ hold time from $\overline{OE}$, read cycle	t_{CHO}	45		55		70		ns	
$\overline{OE}$ setup time to $\overline{CE}$, write cycle	t_{OES}	0		0		0		ns	
$\overline{OE}$ hold time from $\overline{CE}$, write cycle	t_{OEH}	0		0		0		ns	

AC Characteristics (cont)

$T_A = 0$ to $+70°C$, $V_{CC} = 5V \pm 10\%$

Parameter	Symbol	Limits μPD4168-12 Min	Limits μPD4168-12 Max	Limits μPD4168-15 Min	Limits μPD4168-15 Max	Limits μPD4168-20 Min	Limits μPD4168-20 Max	Unit	Test Conditions
$\overline{CE}$ delay to $\overline{RFSH}$, pulse refresh	t_{CRD}	50		65		80		ns	
$\overline{RFSH}$ pulse width, pulse refresh	t_{RDP}	50	4000	65	4000	80	4000	ns	
$\overline{RFSH}$ recovery time, pulse refresh	t_{RPR}	90		100		120		ns	
$\overline{RFSH}$ pulse width, self refresh	t_{RDS}	40		40		40		μs	(Note 8)
$\overline{RFSH}$ recovery time, self refresh	t_{RSR}	2		2		2		μs	
$\overline{CE}$ hold time from $\overline{RFSH}$, self refresh	t_{CSH}	40		40		40		μs	
$\overline{CE}$ setup time to $\overline{RFSH}$, self refresh	t_{CSS}	35		40		50		ns	
Transition time, rise and fall	t_T	3	50	3	50	3	50	ns	(Note 4)
Refresh period	t_{REF}		2		2		2	ms	
$\overline{RFSH}$ precharge time	t_{RP}	90		100		120		ns	
$\overline{OE}$ lead time to refresh cycle	t_{OEL}	170		210		260		ns	
$\overline{WE}$ lead time to refresh cycle	t_{WEL}	170		210		260		ns	
$\overline{RFSH}$ setup time to $\overline{CE}$	t_{RC}	280		320		410		ns	

Note:

(1) All voltages referenced to GND (0 V).

(2) An initial pause of 2 ms is required after power up, followed by any 8 $\overline{CE}$ cycles and 64 $\overline{RFSH}$ cycles before proper device operation is achieved. Read, write, and external refresh cycles may be used as $\overline{CE}$ dummy cycles for initialization. The 64 refresh dummy cycles can be performed before or after the 8 $\overline{CE}$ dummy cycles. Both dummy cycles must be within AC parameters. See figure 1, below.

(3) AC measurements assume $t_T = 5$ ns.

(4) V_{IH} (min) and V_{IL} (max) are reference levels for measuring input signal timing. Transition times are measured between V_{IH} and V_{IL}.

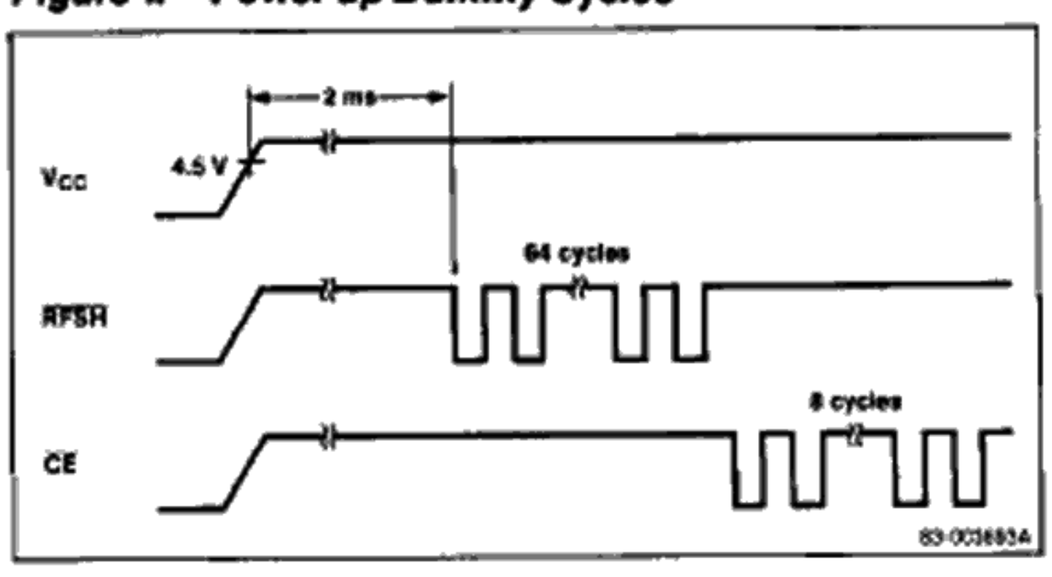
(5) Load = 2 TTL loads and 50 pF.

(6) t_{CEZ} (max) and t_{OEZ} (max) define the time at which the output achieves the open circuit condition and are not referenced to V_{OH} or V_{OL}.

(7) $t_{WSC} \leq t_{WSC}$ (min), the cycle is a late write cycle.

(8) A power down self-refresh cycle is initiated when the $\overline{RFSH}$ input is active low for a period of 40 μs. The refresh interval is about 15.6 μs.

Figure 1. Power-up Dummy Cycles



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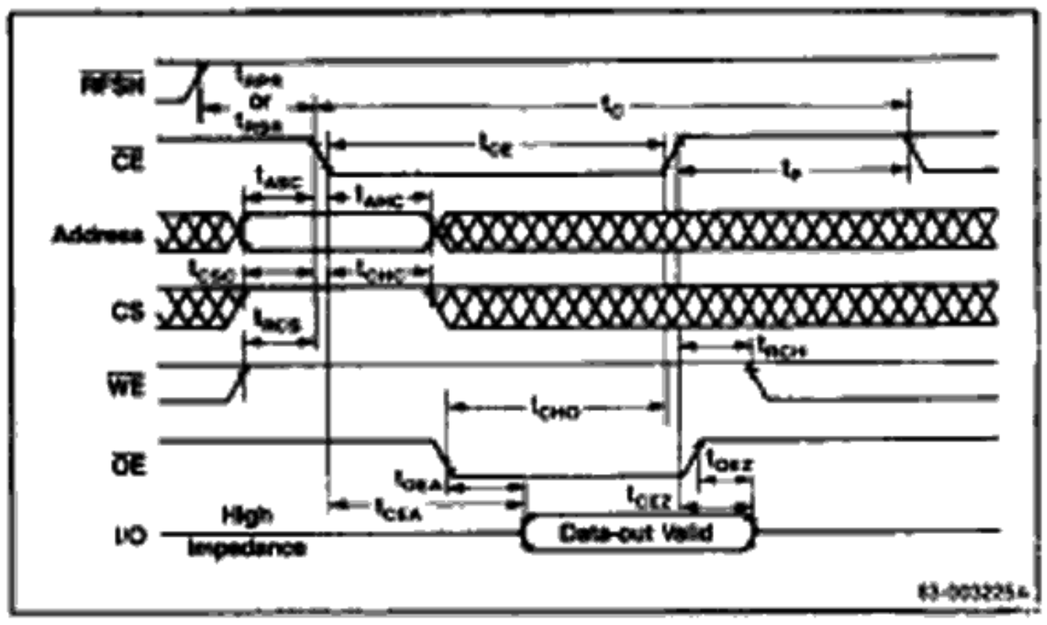
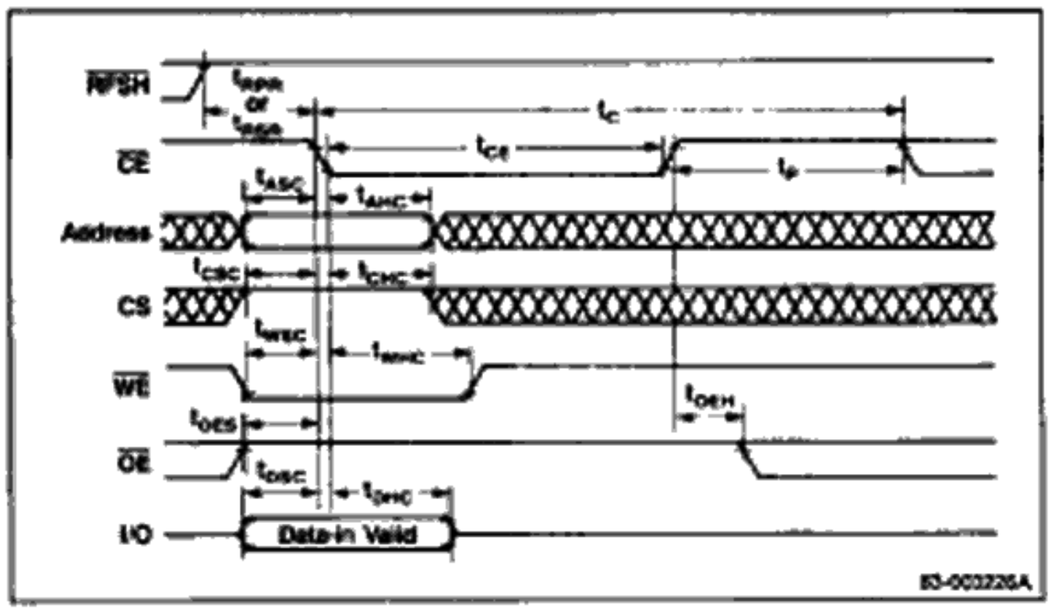
Timing Waveforms

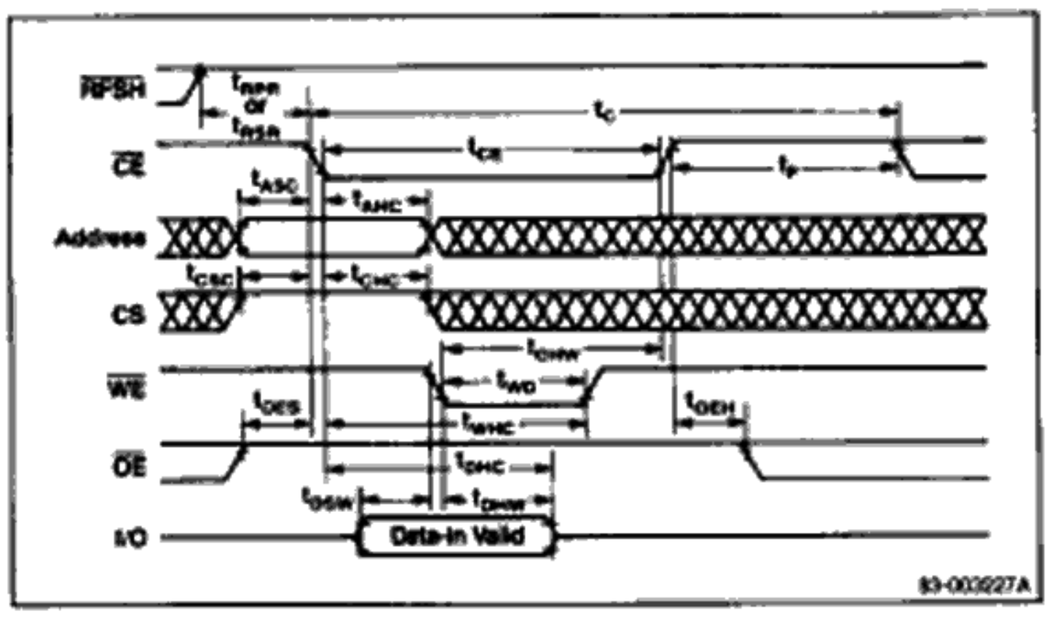
Read Cycle



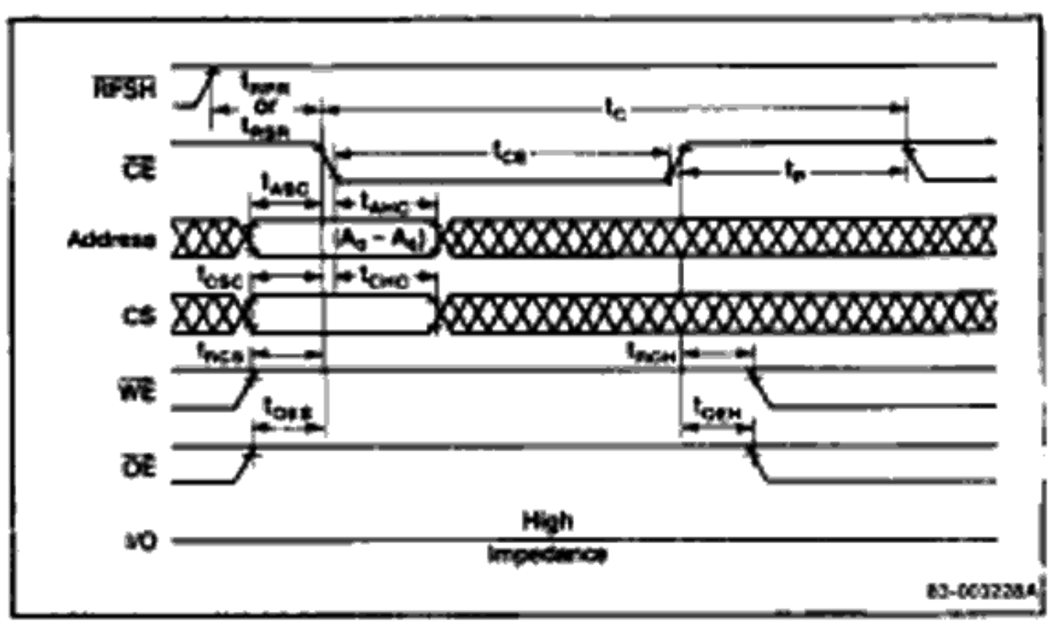
Early Write Cycle



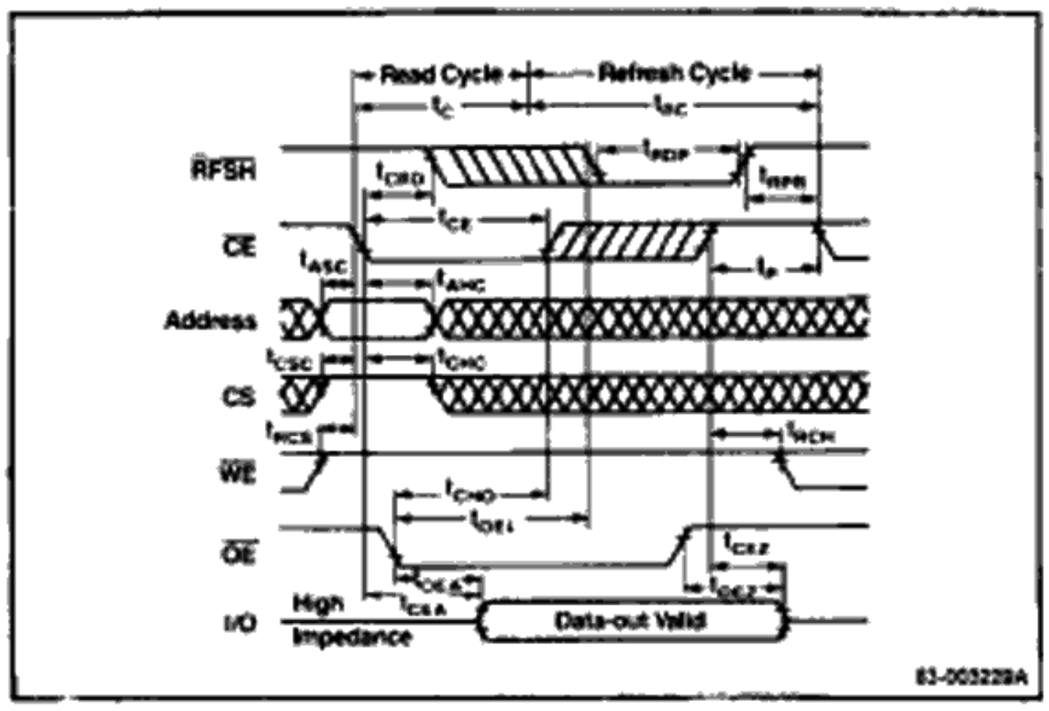
Late Write Cycle



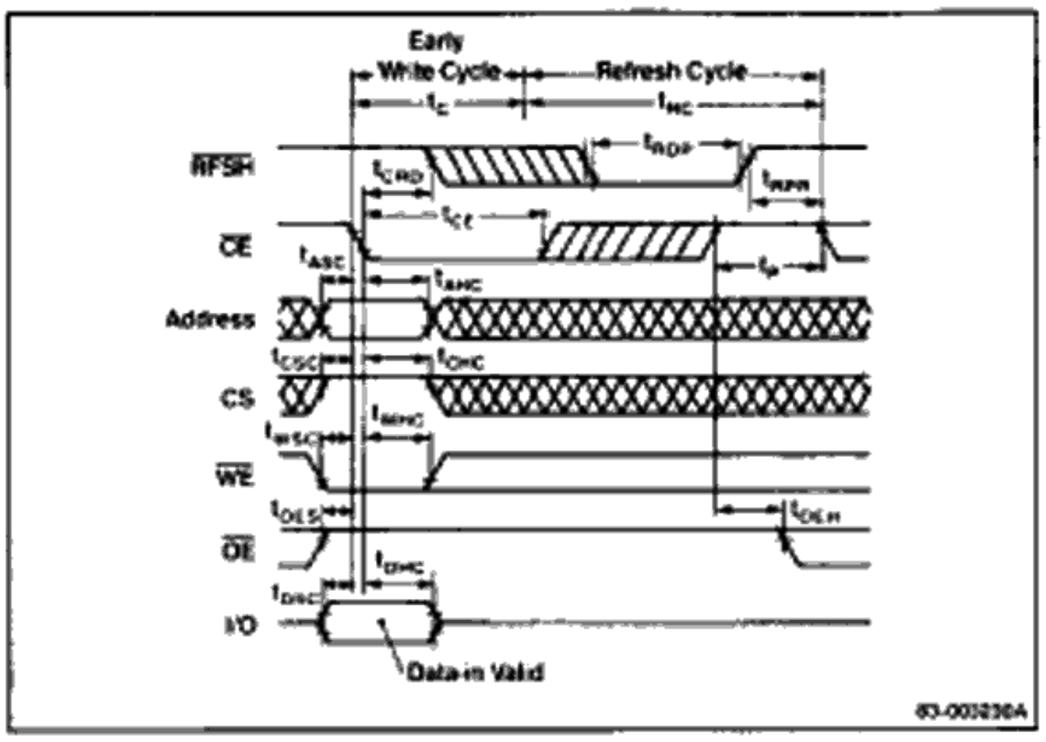
External Refresh Cycle



Pulse Refresh Cycle after Read Cycle Complete

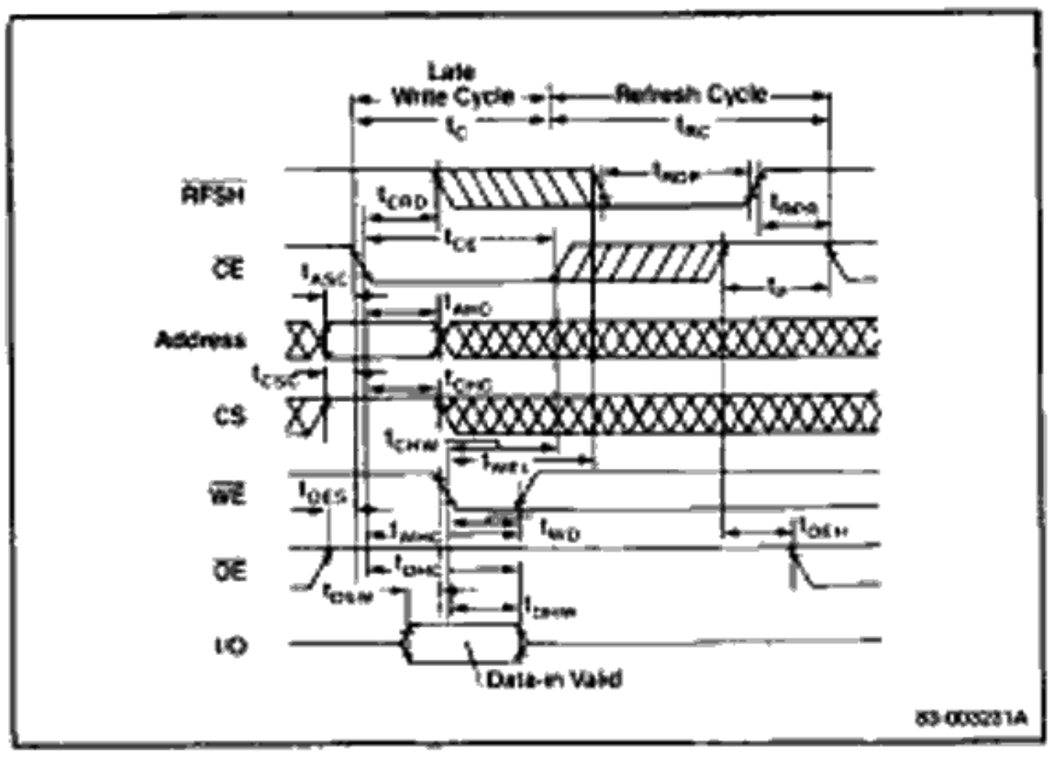


Pulse Refresh Cycle after Early Write Cycle Complete

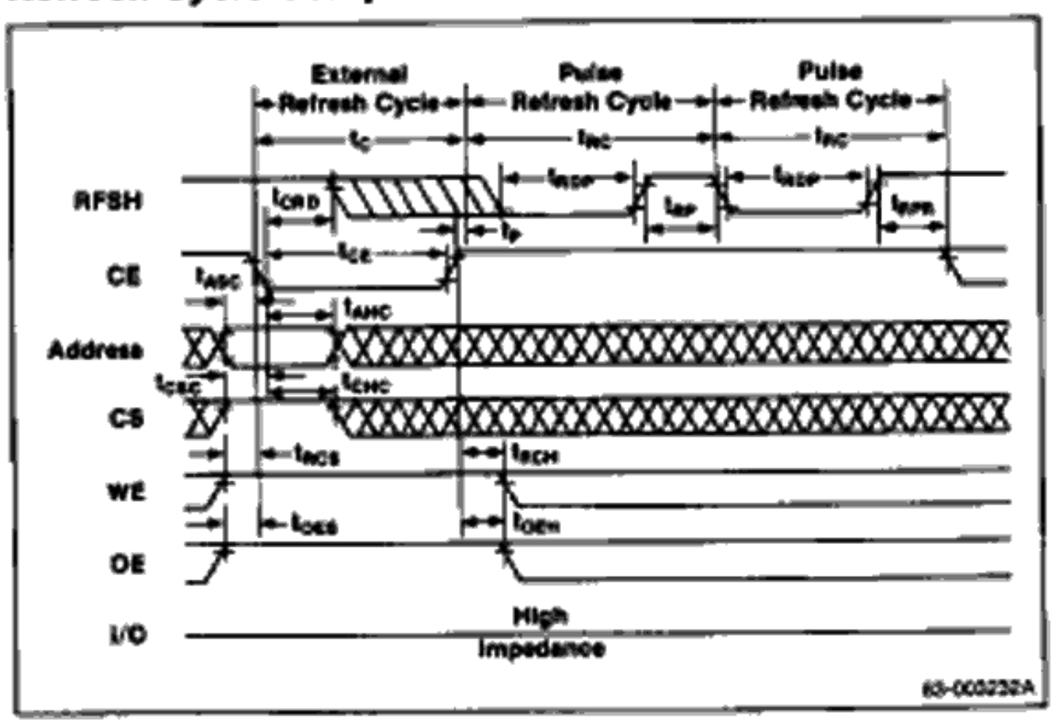


Timing Waveforms (cont)

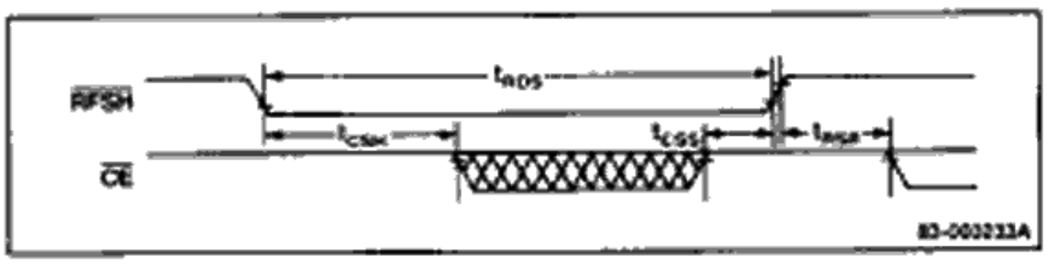
Pulse Refresh Cycle after Late Write Cycle Complete



Pulse Refresh Cycle after External Refresh Cycle Complete



Power-down Self Refresh



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